

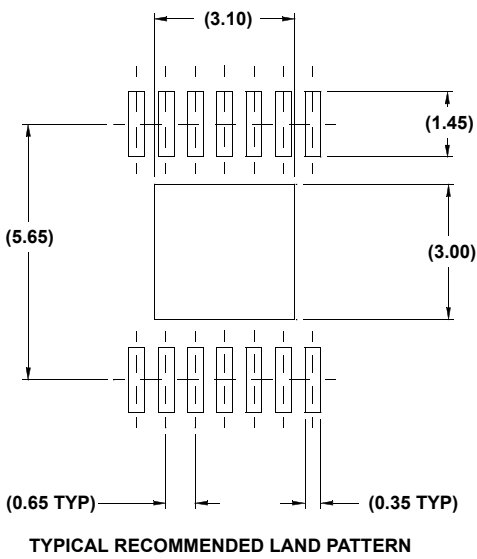
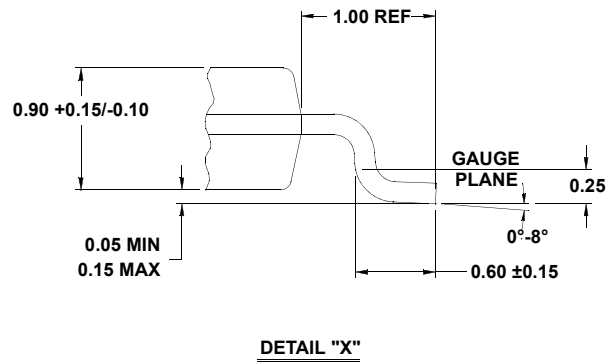
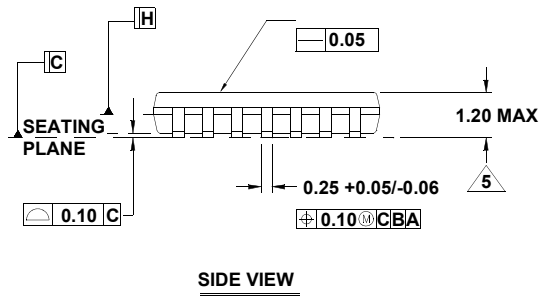
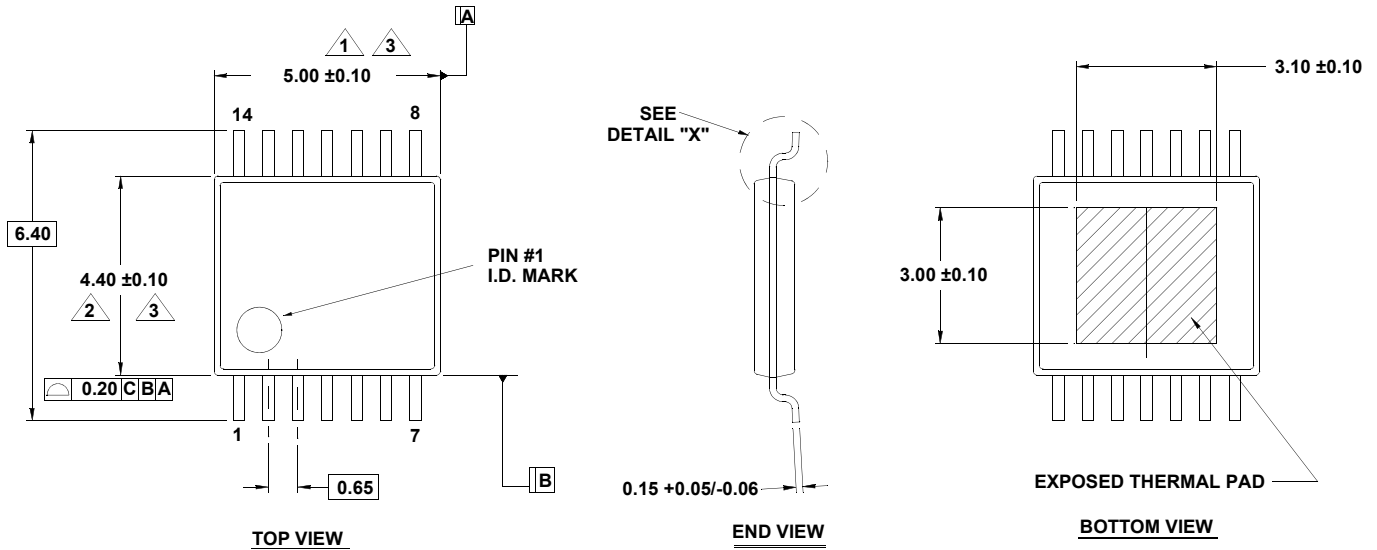
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

### M14.173B

14 LEAD HEATSINK THIN SHRINK SMALL OUTLINE PACKAGE (HTSSOP)

Rev 1, 1/10



#### NOTES:

- Dimension does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 per side.
- Dimension does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25 per side.
- Dimensions are measured at datum plane H.
- Dimensioning and tolerancing per ASME Y14.5M-1994.
- Dimension does not include dambar protrusion. Allowable protrusion shall be 0.80mm total in excess of dimension at maximum material condition. Minimum space between protrusion and adjacent lead is 0.07mm.
- Dimension in ( ) are for reference only.
- Conforms to JEDEC MO-153, variation ABT-1.